

AMENDMENTS

In the Specification:

Page 2, please amend paragraph [0007] as follows:

[0007] In another aspect of the present invention there is provided an integrated circuit package. The integrated circuit package includes ~~a~~first a first leadframe, a second leadframe laminated to a portion of the first leadframe in order to create a multi-layer laminated leadframe, and a semiconductor die mounted to another portion of the first leadframe.